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PD_FB_01

ISO-Projektion
 Methode 1

1 2 3 4

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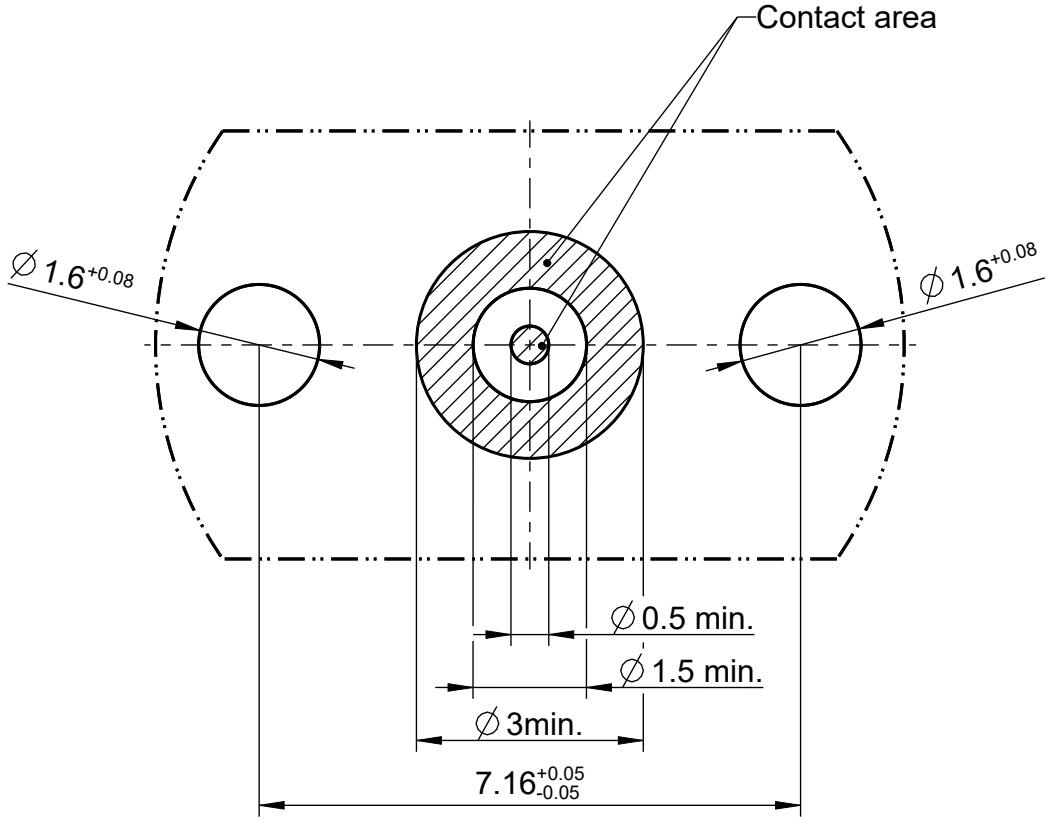
C

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Leiterplatten Layout
 PCB layout
 B 594A



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Die angegebenen Maße und Toleranzen sind nur Empfehlungen.
 The stated dimensions are only recommendations.

Rosenberger		general tolerance		assembly instr.: ---		scale: 10:1 ()		crimp insert: ---	
		ISO 2768 mH		panel piercing: ---		series: RPC-2.92		cable: ---	
vertraulich / confidential				date		name		title: Leiterplatten Layout PCB layout	
				drawn	06.02.2017	M_Knoll			
				check.	13.11.2018	G_Schiele			
				appr.	13.11.2018	M_Moder			
b00	18-2035	M_Ruf	12.11.2018	drawing-no.: MB_594A				sheet: 1	
a00	18-s133	M_Ruf	23.03.2018					of: 1	
100	17-v115	M_Knoll	06.02.2017	remarks: MB_594					
rev.	change-no	name	date						

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